

Total No. of Questions : 10]

SEAT No. :

P4943

[Total No. of Pages :2

[4959]-1120
B.E. (Electronics)
C : SYSTEMS ON CHIP
(2012 Pattern) (Semester - II)

Time : 2.30 Hours]

[Maximum Marks : 70

Instructions to the candidates:

- 1) *Answer Q.1 or Q.2, Q.3 or Q.4, Q.5 or Q.6, Q.7 or Q.8, Q.9 or Q.10.*
- 2) *Draw neat diagrams.*
- 3) *Assume suitable data, if necessary.*

- Q1)** a) How to avoid data loss using FIFO? What are its limitations? [6]
- b) Which factors acted as barriers to the use of the Microsystems technology? [4]

OR

- Q2)** a) Explain in the TRIMEDIA processor specifications and performance metrics. [6]
- b) Why latches should be avoided in design? What is good practice to avoid latches? [4]

OR

- Q3)** a) What do you mean by loop folding? Explain it in context with constraint propagation and interval analysis. [6]
- b) Why at RTL stage, it is very difficult to know the actual delays? [4]
- Q4)** a) Explain with example constraint propagation. [6]
- b) What is the reason of this pre and post synthesis simulation mismatch?[4]

P.T.O.

- Q5)** a) Which factors plays important role while developing mathematical model for analysis of MEMS? [8]
- b) Explain Structured Design Methods for MEMS? [8]

OR

- Q6)** a) What do you mean by scaling in electromagnetic force? Justify: electromagnetic force is $F \propto l^4$. [8]
- b) Compare GaAs Vs Silicon. [8]

- Q7)** a) Explain pros and cons of behavioral synthesis. [8]
- b) Explain abstraction levels in contact to synthesis tool. [8]

OR

- Q8)** a) Compare of bulk-and surface-micromachining processes for MEMS fabrication. [8]
- b) What are wet-etch selection and development principles? [8]

- Q9)** a) Explain the terms- [9]
- i) Defects and fault method
- ii) Fault simulation
- b) What are the issues in testing of core based systems on chip? [9]

OR

- Q10)**a) Explain features of co-design tool with an example. [9]
- b) What are the requirements of packaging? Which materials are used at this stage? [9]

